

SN74CB3Q3384A 10-Bit FET Bus Switch

2.5V/3.3V Low-voltage High-bandwidth Bus Switch

1 Features

- High-Bandwidth Data Path (up to 500MHz)
- 5V Tolerant I/Os With Device Powered Up or Powered Down
- Low and Flat ON-State Resistance (r_{on}) Characteristics Over Operating Range ($r_{on} = 3\Omega$ Typ)
- Rail-to-Rail Switching on Data I/O Ports
 - 0- to 5V Switching With 3.3V V_{CC}
 - 0- to 3.3V Switching With 2.5V V_{CC}
- Bidirectional Data Flow With Near-Zero Propagation Delay
- Low Input/Output Capacitance Minimizes Loading and Signal Distortion ($C_{io(OFF)} = 4pF$ Typ)
- Fast Switching Frequency ($f_{OE} = 20MHz$ Max)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ($I_{CC} = 1mA$ Typ)
- V_{CC} Operating Range From 2.3V to 3.6V
- Data I/Os Support 0- to 5V Signaling Levels (0.8V, 1.2V, 1.5V, 1.8V, 2.5V, 3.3V, 5V)
- Control Inputs Can Be Driven by TTL or 5V/3.3V CMOS Outputs
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000V Human-Body Model (A114-B, Class II)
 - 1000V Charged-Device Model (C101)
- Supports Both Digital and Analog Applications: PCI Interface, Differential Signal Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating

2 Description

The SN74CB3Q3384A is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and

flat ON-state resistance (r_{on}). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q3384A provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.

The SN74CB3Q3384A is organized as two 5-bit bus switches with separate output-enable (1 $\overline{OE}$, 2 $\overline{OE}$) inputs. It can be used as two 5-bit bus switches or as one 10-bit bus switch. When $\overline{OE}$ is low, the associated 5-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When $\overline{OE}$ is high, the associated 5-bit bus switch is OFF, and a high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry prevents damaging current backflow through the device when it is powered down. The device has isolation during power off.

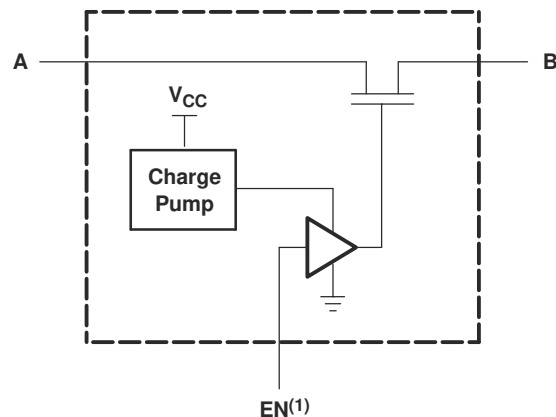
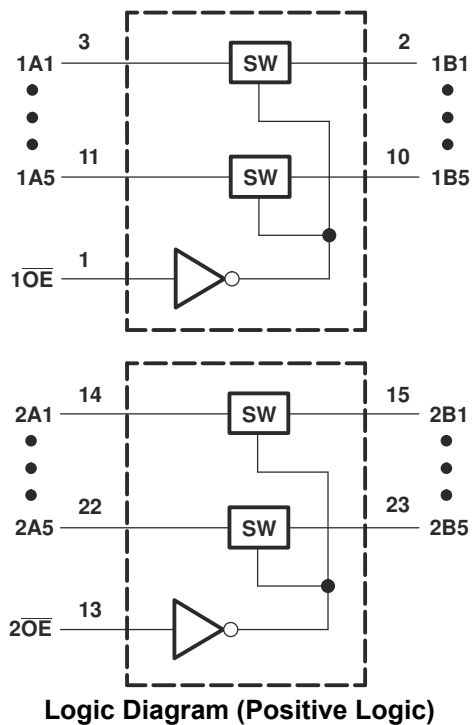
To ensure the high-impedance state during power up or power down, $\overline{OE}$ must be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Package Information

T_A	PACKAGE ⁽¹⁾	PACKAGE SIZE	PART NUMBER
–40°C to 85°C	DBQ(24, QSOP)	8.65mm × 6mm	SN74CB3Q3384A
	PW(24, TSSOP)	7.8mm × 6.4mm	
	DGV(24, TVSOP)	5mm × 6.4mm	

(1) For more information, see [Section 8](#).





(1) EN is the internal enable signal applied to the switch.

Simplified Schematic, Each FET Switch (SW)

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3 Pin Configuration and Functions

DBQ, DGV, OR PW PACKAGE
(TOP VIEW)

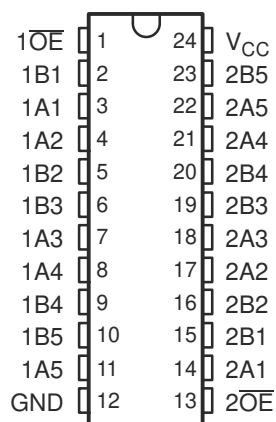


Figure 3-1. Pinout

Table 3-1. Function Table
(Each 5-Bit BUS Switch)

INPUT OE	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect

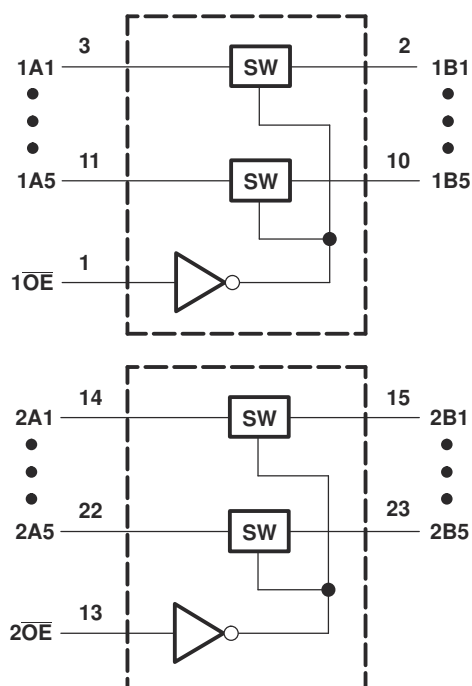
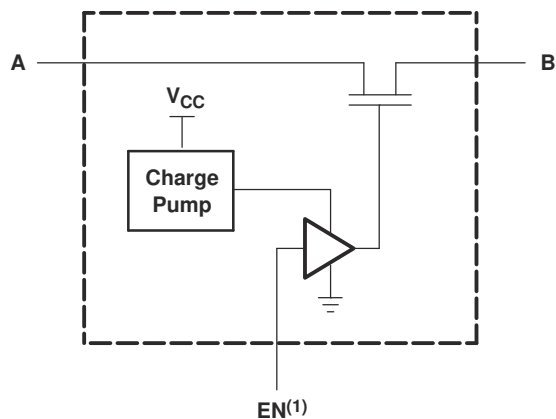


Figure 3-2. Logic Diagram (Positive Logic)



(1) EN is the internal enable signal applied to the switch.

Figure 3-3. Simplified Schematic, Each FET Switch (SW)

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	−0.5	4.6	V
V _{IN}	Control input voltage range ^{(2) (3)}	−0.5	7	V
V _{I/O}	Switch I/O voltage range ^{(2) (3) (4)}	−0.5	7	V
I _{IK}	Control input clamp current	V _{IN} < 0	−50	mA
I _{I/OK}	I/O port clamp current	V _{I/O} < 0	−50	mA
I _{I/O}	ON-state switch current ⁽⁵⁾		±64	mA
I _O	Continuous current through V _{CC} or GND		±100	mA
θ _{JA}	Package thermal impedance ⁽⁶⁾	DBQ package	83.7	°C/W
		DGV package	86	
		PW package	93.4	
T _{stg}	Storage temperature range	−65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V_I and V_O are used to denote specific conditions for V_{I/O}.
- (5) I_I and I_O are used to denote specific conditions for I_{I/O}.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

4.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

4.3 Recommended Operating Conditions

(1)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3V to 2.7V	1.7	5.5
		V _{CC} = 2.7V to 3.6V	2	5.5
V _{IL}	Low-level control input voltage	V _{CC} = 2.3V to 2.7V	0	0.7
		V _{CC} = 2.7V to 3.6V	0	0.8
V _{I/O}	Data input/output voltage	0	5.5	V
T _A	Operating free-air temperature	−40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application note, [Implications of Slow or Floating CMOS Inputs](#).

4.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74CB3Q3384A			UNIT
		DBQ (QSOP)	DGV (TVSOP)	PW (TSSOP)	
		24 PINS	24 PINS	24 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	83.7	86	93.4	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application note.

4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
V _{IK}		V _{CC} = 3.6V,	I _I = –18mA			–1.8	V
I _{IN}	Control inputs	V _{CC} = 3.6V,	V _{IN} = 0 to 5.5V			±1	μA
I _{OZ} ⁽³⁾		V _{CC} = 3.6V,	V _O = 0 to 5.5V, V _I = 0, Switch OFF, V _{IN} = V _{CC} or GND			±1	μA
I _{off}		V _{CC} = 0,	V _O = 0 to 5.5V, V _I = 0			1	μA
I _{CC}		V _{CC} = 3.6V,	I _{I/O} = 0, Switch ON or OFF, V _{IN} = V _{CC} or GND		1	2	mA
ΔI _{CC} ⁽⁴⁾	Control inputs	V _{CC} = 3.6V,	One input at 3V, Other inputs at V _{CC} or GND			30	μA
I _{CCD} ⁽⁵⁾	Per control input	V _{CC} = 3.6V, Control input switching at 50% duty cycle	A and B ports open,		0.27	0.33	mA/ MHz
C _{in}	Control inputs	V _{CC} = 3.3V,	V _{IN} = 5.5V, 3.3V, or 0		2.5	3.5	pF
C _{io(OFF)}		V _{CC} = 3.3V,	Switch OFF, V _{IN} = V _{CC} or GND, V _{I/O} = 5.5V, 3.3V, or 0		3.5	5	pF
C _{io(ON)}		V _{CC} = 3.3V,	Switch ON, V _{IN} = V _{CC} or GND, V _{I/O} = 5.5V, 3.3V, or 0		8	10	pF
r _{on} ⁽⁶⁾		V _{CC} = 2.3V, TYP at V _{CC} = 2.5V	V _I = 0, I _O = 30mA		3	8	Ω
			V _I = 1.7V, I _O = –15mA		3.5	9	
		V _{CC} = 3V	V _I = 0, I _O = 30mA		3	6	
			V _I = 2.4V, I _O = –15mA		3.5	8	

- (1) V_{IN} and I_{IN} refer to control inputs. V_I, V_O, I_I, and I_O refer to data pins.
(2) All typical values are at V_{CC} = 3.3V (unless otherwise noted), T_A = 25°C.
(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.
(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.
(5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see [Figure 4-2](#)).
(6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

4.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		UNIT
			MIN	MAX	MIN	MAX	
$f_{OE}^{(1)}$	$\overline{OE}$	A or B		10		20	MHz
$t_{pd}^{(2)}$	A or B	B or A		0.09		0.15	ns
t_{en}	$\overline{OE}$	A or B	1.5	8.7	1.5	6.8	ns
t_{dis}	$\overline{OE}$	A or B	1.5	17.6	1.5	12.1	ns

- (1) Maximum switching frequency for control input ($V_O > V_{CC}$, $V_I = 5V$, $R_L \geq 1M\Omega$, $C_L = 0$)
 (2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

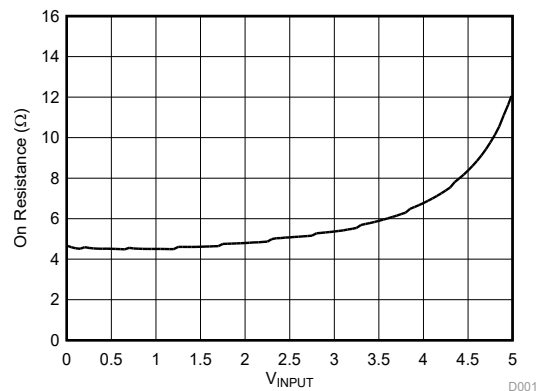


Figure 4-1. Typical r_{on} vs V_I

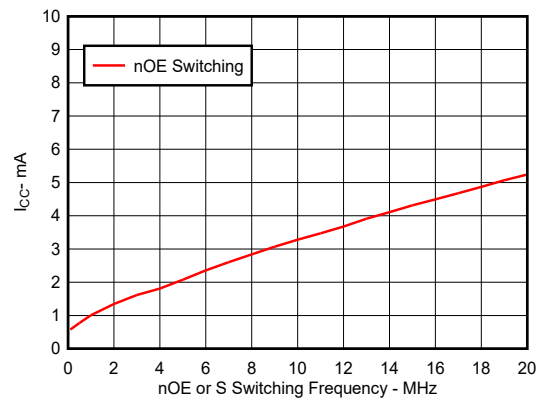
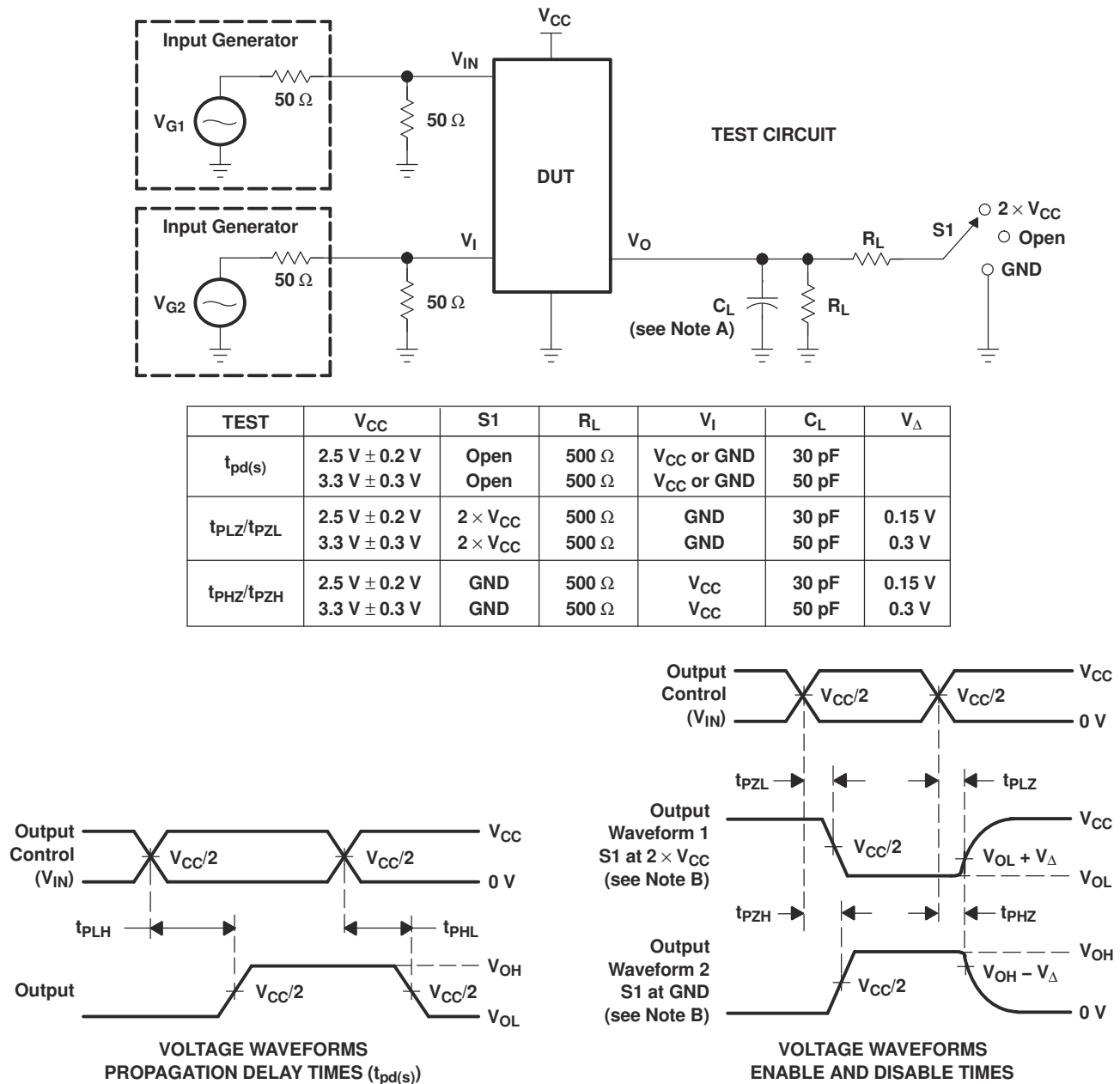


Figure 4-2. Typical I_{CC} vs $\overline{OE}$ Switching Frequency

5 Parameter Measurement Information



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - t_{PZL} and t_{PZH} are the same as t_{en}.
 - t_{PLH} and t_{PHL} are the same as t_{pd(s)}. The t_{pd} propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
 - All parameters and waveforms are not applicable to all devices.

Figure 5-1. Test Circuit and Voltage Waveforms

6 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

6.1 Documentation Support

6.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

6.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

6.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

6.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

6.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (November 2003) to Revision E (September 2026)	Page
• Updated the number formatting for tables, figures, and cross-references throughout the document.....	1
• Removed Ordering Information table.....	1
• Added ESD Ratings table.....	6
• Added the <i>Thermal Information</i> table and moved $R_{\theta JA}$ values to the table.....	7
• Updated the maximum per control input parameter in <i>Electrical Characteristics</i>	7
• Updated the maximum V_{CC} rating for t_{en} and t_{dis} in the <i>Switching Characteristics</i> table.....	8

8 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74CB3Q3384ADGVRG4	Active	Production	TVSOP (DGV) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
74CB3Q3384ADGVRG4.B	Active	Production	TVSOP (DGV) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
SN74CB3Q3384ADBQR	Active	Production	SSOP (DBQ) 24	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CB3Q3384A
SN74CB3Q3384ADBQR.A	Active	Production	SSOP (DBQ) 24	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CB3Q3384A
SN74CB3Q3384ADBQR.B	Active	Production	SSOP (DBQ) 24	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CB3Q3384A
SN74CB3Q3384ADGVR	Active	Production	TVSOP (DGV) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
SN74CB3Q3384ADGVR.B	Active	Production	TVSOP (DGV) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
SN74CB3Q3384APW	Obsolete	Production	TSSOP (PW) 24	-	-	Call TI	Call TI	-40 to 85	BU384A
SN74CB3Q3384APWR	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
SN74CB3Q3384APWR.A	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A
SN74CB3Q3384APWR.B	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU384A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74CB3Q3384ADGVRG4	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CB3Q3384ADBQR	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CB3Q3384ADGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CB3Q3384APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

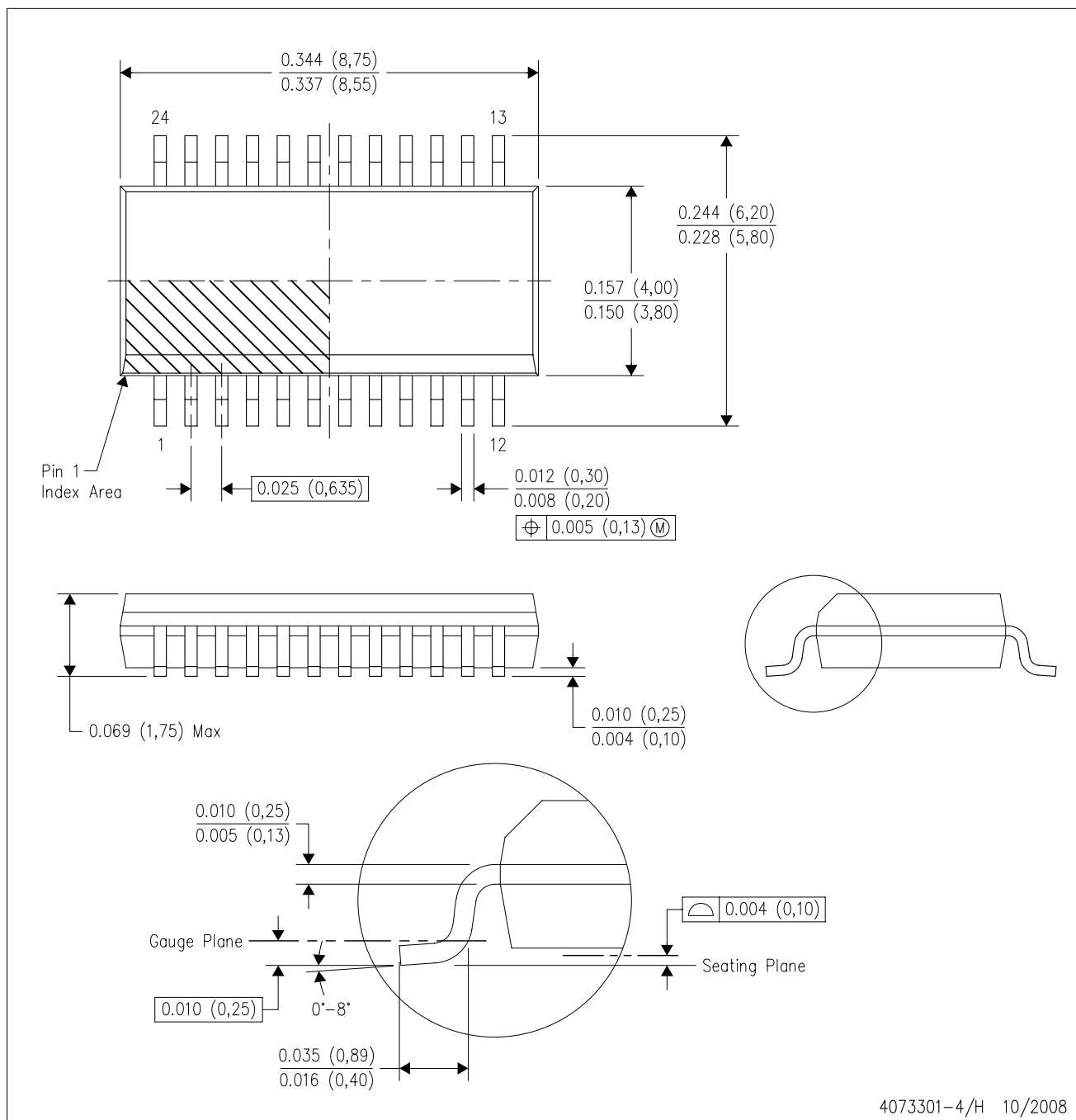


*All dimensions are nominal

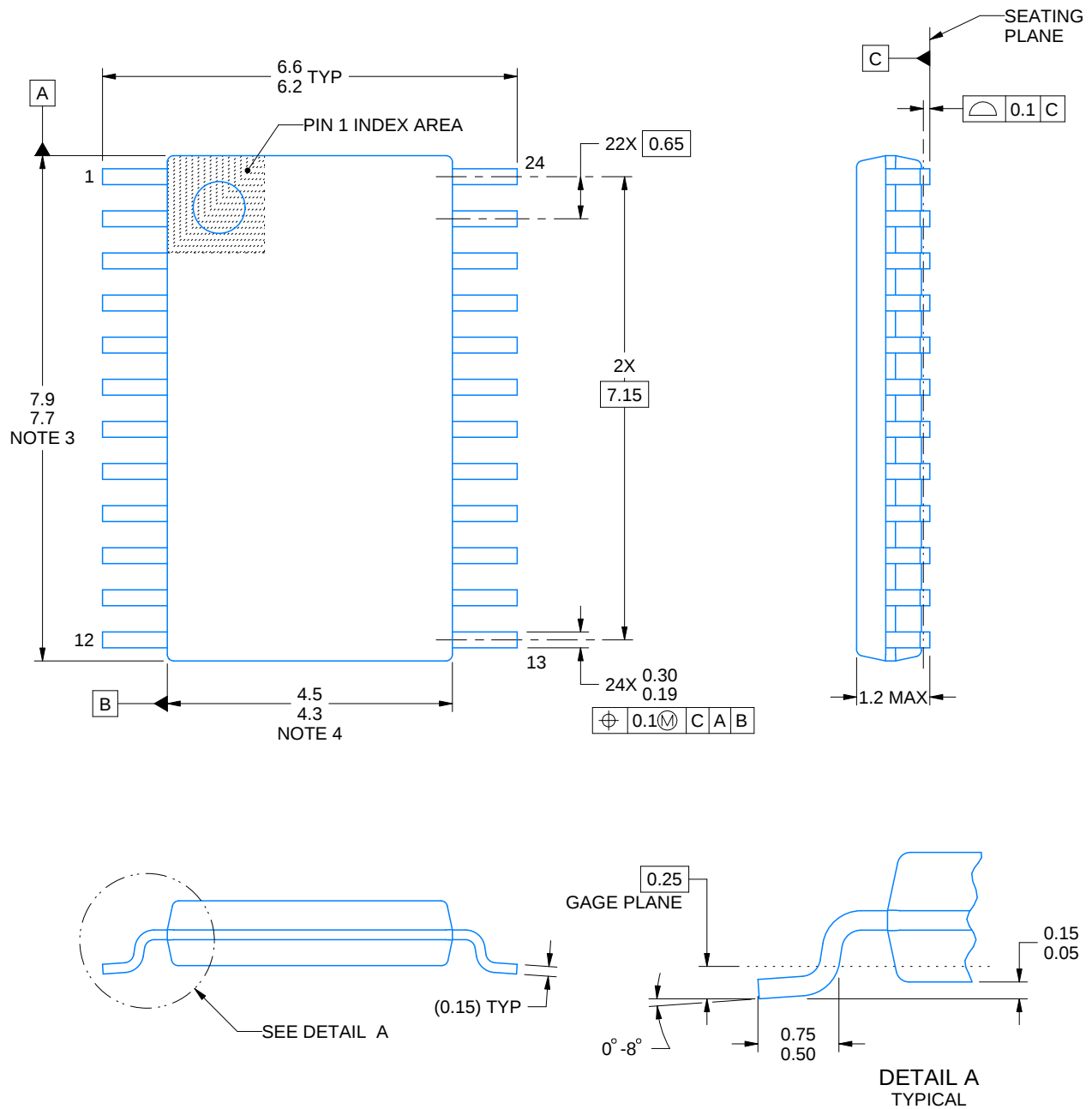
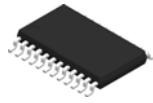
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74CB3Q3384ADGVRG4	TVSOP	DGV	24	2000	353.0	353.0	32.0
SN74CB3Q3384ADBQR	SSOP	DBQ	24	2500	353.0	353.0	32.0
SN74CB3Q3384ADGVR	TVSOP	DGV	24	2000	353.0	353.0	32.0
SN74CB3Q3384APWR	TSSOP	PW	24	2000	353.0	353.0	32.0

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AE.



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NOTES:

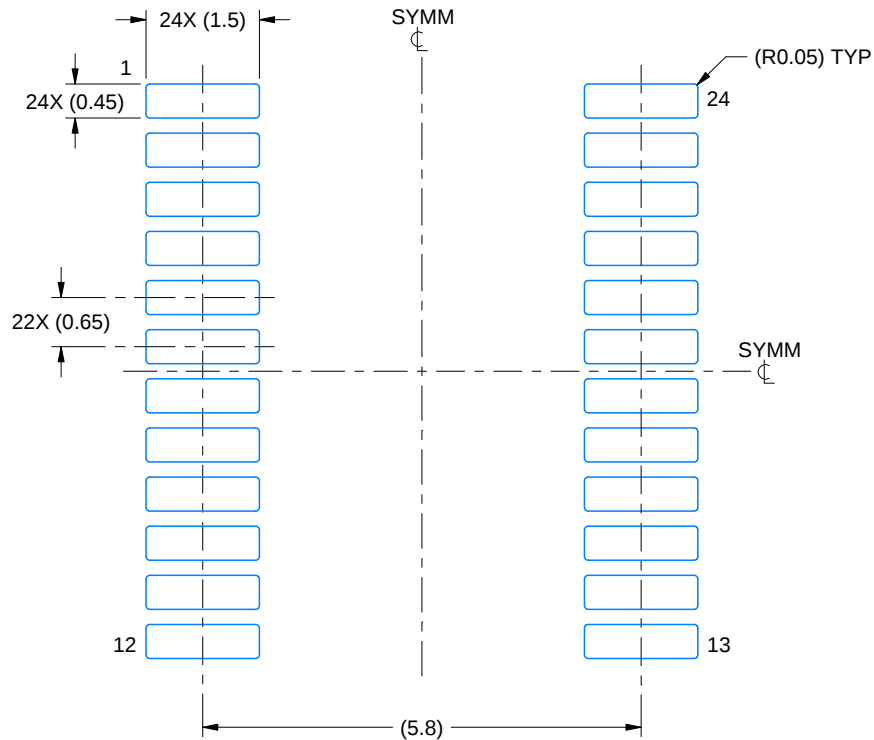
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

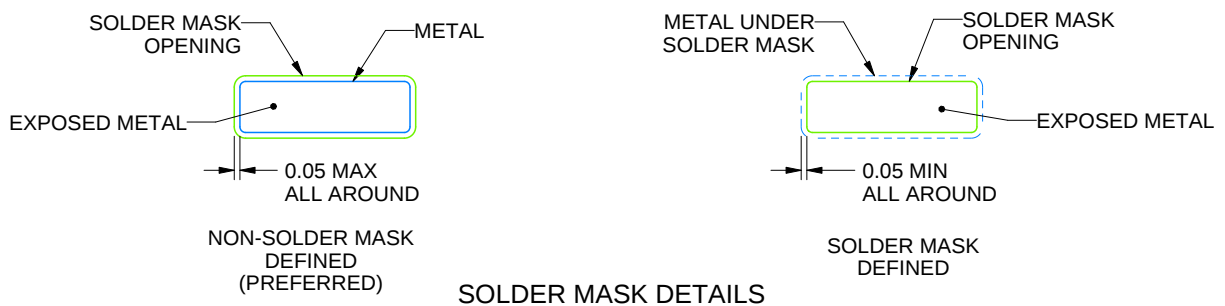
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

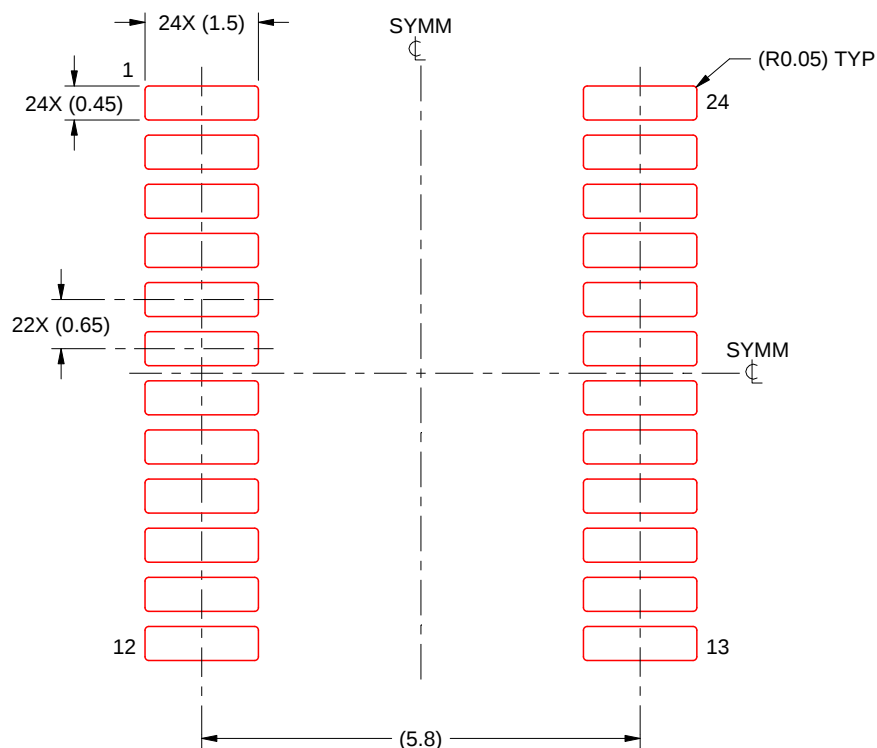
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

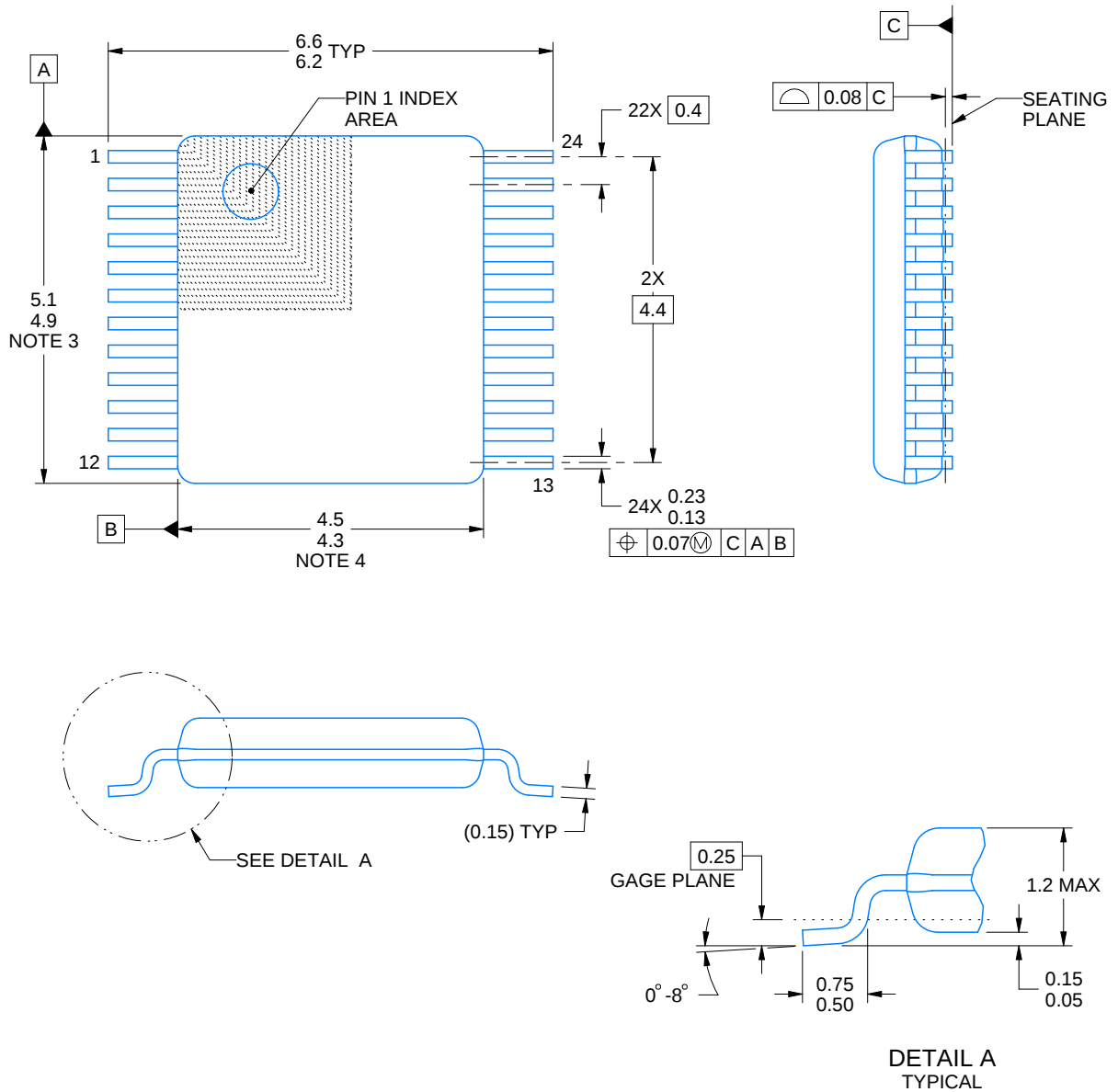
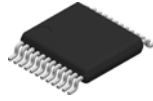


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4229221/A 12/2022

NOTES:

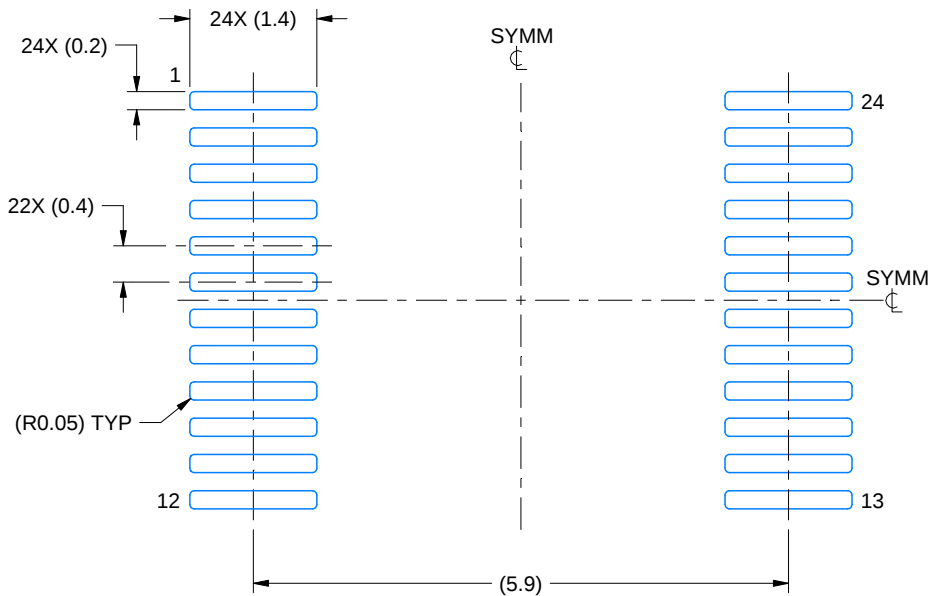
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

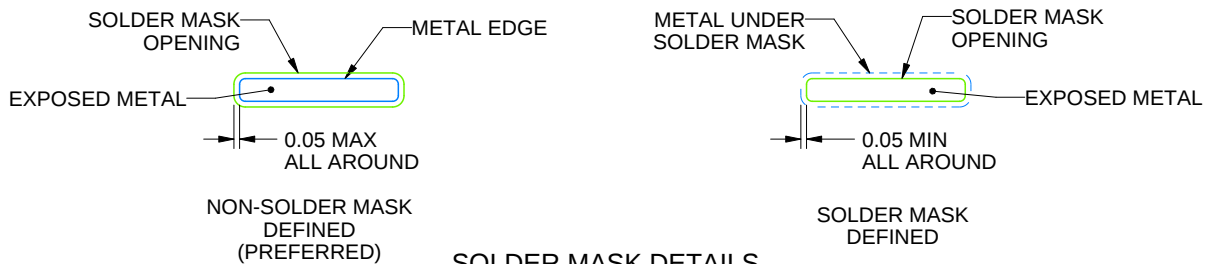
DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 12X



SOLDER MASK DETAILS

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NOTES: (continued)

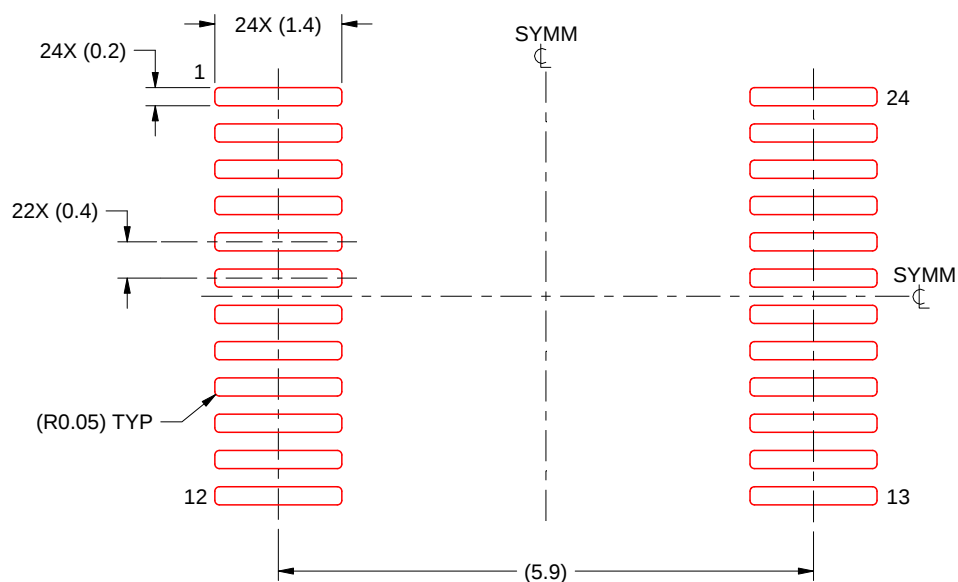
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 12X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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